

IN THE CLAIMS

Please amend claims 1-4, 6, 8, 12-15, 18 and cancel claims 9, 10, 11, 16, 19 and 20 as follows.

Claim 1 (Currently Amended): A gradient coil assembly for use in an MRI device, comprising:

~~a gradient tube extending along an axis, the tube including first and second gradient coils and a conductive compound disposed between the first and second gradient coils, the conductive compound being a glue having a plurality of conductive particles therein, at least a portion of the plurality of conductive particles being in a range of 1-10 μ m in diameter, the plurality of conductive particles configured to limit a current flowing through the conductive compound to less than 10 microamps to reduce electrostatic discharges in the glue.~~

Claim 2 (Currently Amended): The gradient coil assembly of claim 1 wherein the ~~conductive compound glue~~ comprises an epoxy resin having a plurality of conductive particles.

Claim 3 (Currently Amended): The gradient coil assembly of claim 2 wherein the conductive particles comprise one of carbon particles, silver particles, copper particles, and gold particles.

Claim 4 (Currently Amended): The gradient coil assembly of claim 2 wherein the conductive compound further includes a chemical hardening compound.

Claim 5 (Original): The gradient coil assembly of claim 2 wherein the epoxy resin comprises a bisphenol-A resin.

Claim 6 (Currently Amended): The gradient coil assembly of claim 1 wherein the ~~conductive compound glue~~ comprises a polyester resin having a plurality of conductive particles.

Claim 7 (Original): The gradient coil assembly of claim 6 wherein the conductive particles comprise one of carbon particles, silver particles, copper particles, and gold particles.

Claim 8 (Currently Amended): The gradient coil assembly of claim 6 wherein the ~~conductive compound~~ further includes a chemical hardening compound.

Claim 9 (Cancelled).

Claim 10 (Cancelled).

Claim 11 (Cancelled).

Claim 12 (Currently Amended): A gradient coil assembly for use in an MRI device, comprising:

a gradient tube extending along an axis, the tube including first and second gradient coils and a potting compound layer disposed between the first and second gradient coils, the potting compound layer having a plurality of conductive particles configured to limit a current flowing through the potting compound layer to less than a predetermined current value to reduce electrostatic discharges in the potting compound layer, the plurality of conductive particles being at least one of silver particles and gold particles.

Claim 13 (Currently Amended): A method for assembling a gradient coil assembly, comprising:

disposing a first gradient coil on a first gradient tube; and

disposing a conductive compound between the first gradient coil and a second gradient coil, the conductive compound being a glue having a plurality of conductive particles therein, at least a portion of the plurality of conductive particles being in a range of 1-10 μ m in diameter, the plurality of conductive particles configured to limit a current flowing through the conductive compound to less than a predetermined value to reduce electrostatic discharges in the glue, the conductive compound further having a chemical hardening compound therein.

Claim 14 (Currently Amended): The method of claim 13 wherein the disposing a the conductive compound layer includes vacuum impregnating the conductive compound between the first and second gradient coils.

Claim 15 (Currently Amended): The method of claim 13 wherein the conductive compound glue comprises an epoxy resin having a plurality of conductive particles.

Claim 16 (Cancelled).

Claim 17 (Original): The method of claim 15 wherein the conductive particles comprise one of carbon particles, silver particles, copper particles, and gold particles.

Claim 18 (Currently Amended): The method of claim 13 wherein the ~~conductive compound glue~~ comprises a polycaprolactone resin having a plurality of conductive particles.

Claim 19 (Cancelled).

Claim 20 (Cancelled).